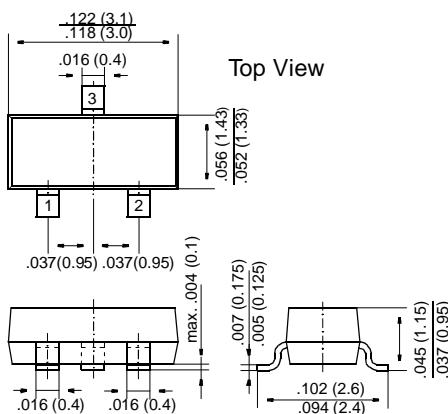


BS809

DMOS Transistors (N-Channel)

SOT-23



Dimensions in inches and (millimeters)

Pin configuration

1 = Gate, 2 = Source, 3 = Drain

FEATURES

- ◆ High input impedance
- ◆ Low gate threshold voltage
- ◆ Low drain-source ON resistance
- ◆ High-speed switching
- ◆ No minority carrier storage time
- ◆ CMOS logic compatible input
- ◆ No thermal runaway
- ◆ No secondary breakdown



MECHANICAL DATA

Case: SOT-23 Plastic Package

Weight: approx. 0.008 g

Marking

S09

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	400	V
Drain-Gate Voltage	V _{DGS}	400	V
Gate-Source Voltage (pulsed)	V _{GS}	±20	V
Drain Current (continuous) at T _{SB} = 50 °C	I _D	100	mA
Power Dissipation at T _{SB} = 50 °C	P _{tot}	310 ¹⁾	mW
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _s	-65 to +150	°C

1) Device on fiberglass substrate, see layout

Inverse Diode

	Symbol	Value	Unit
Max. Forward Current (continuous) at T _{amb} = 25 °C	I _F	300	mA
Forward Voltage Drop (typ.) at V _{GS} = 0, I _F = 0.3 A, T _j = 25 °C	V _F	1.0	V

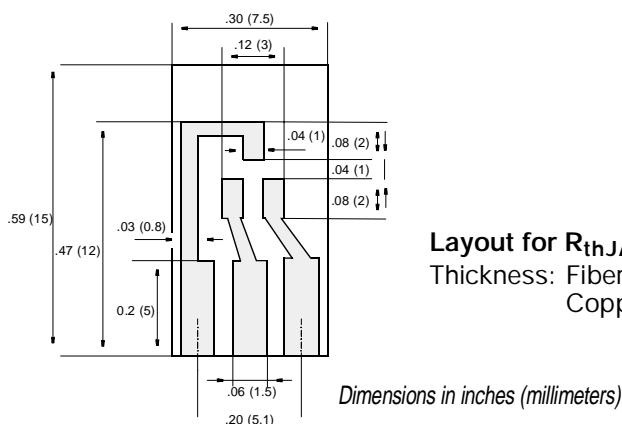
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ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage at $I_D = 100 \mu A$, $V_{GS} = 0 V$	$V_{(BR)DSS}$	400	430	—	V
Gate-Body Leakage Current, Forward at $V_{GSF} = 20 V$, $V_{DS} = 0 V$	I_{GSSF}	—	—	100	nA
Gate-Body Leakage Current, Reverse at $V_{GSR} = 20 V$, $V_{DS} = 0 V$	I_{GSSR}	—	—	100	nA
Drain Cutoff Current at $V_{DS} = 400 V$, $V_{GS} = 0 V$	I_{DSS}	—	—	500	nA
Gate-Source Threshold Voltage at $V_{GS} = V_{DS}$, $I_D = 250 \mu A$	$V_{GS(th)}$	1	1.5	2.5	V
Drain-Source ON Resistance at $V_{GS} = 5 V$, $I_D = 100 mA$	$R_{DS(on)}$	—	18	22	Ω
Capacitances at $V_{DS} = 25 V$, $V_{GS} = 0 V$, $f = 1 MHz$ Input Capacitance Output Capacitance Feedback Capacitance	C_{iss} C_{oss} C_{rs}	— — —	80 20 10	— — —	pF pF pF
Switching Times at $V_{GS} = 10 V$, $V_{DS} = 10 V$, $R_D = 100 \Omega$ Turn-On Time Turn-Off Time	t_{on} t_{off}	— —	10 50	— —	ns ns
Thermal Resistance Junction to Substrate Backside	R_{thSB}			320 ¹⁾	
Thermal Resistance Junction to Ambient Air	R_{thJA}	—	—	450 ¹⁾	K/W

¹⁾ Device on fiberglass substrate, see layout



Layout for R_{thJA} test
Thickness: Fiberglass 0.059 in (1.5 mm)
Copper leads 0.012 in (0.3 mm)

Dimensions in inches (millimeters)